Freescale Semiconductor
Technical Data

MPC7457ECS01AD
Rev. 3, 01/2005

MPC7457 Hardware Specification Addendum for the MPC74*n*7RX*nnnn*N*x* Series

This document describes part-number-specific changes to recommended operating conditions and revised electrical specifications, as applicable, from those described in the general *MPC7457 RISC Microprocessor Hardware Specifications* (Order No. MPC7457EC). The MPC7457 and MPC7447 are implementations of the PowerPC™ microprocessor family of reduced instruction set computer (RISC) microprocessors.

Specifications provided in this document supersede those in the *MPC7457 RISC Microprocessor Hardware Specifications*, Rev. 5 or later, for the part numbers listed in Table A only. Specifications not addressed herein are unchanged. Because this document is frequently updated, refer to http://www.freescale.com or to your Freescale sales office for the latest version.

Note that headings and table numbers in this document are not consecutively numbered. They are intended to correspond to the heading or table affected in the general hardware specification.

Freescale Part Numbers Affected:

MC7447RX1000NB
MC7447RX867NB
MC7447RX733NB
MC7447RX600NB
MC7457RX1000NC
MC7457RX867NC
MC7457RX733NC
MC7457RX600NC

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Part numbers addressed in this document are listed in Table A.

Table A. Part Numbers Addressed by this Data Sheet

Freescale Part Number	Operating Conditions			Significant Differences from Hardware Specification
	CPU Frequency (MHz)	V_{DD}	T_j (°C)	
MC7447RX1000NB	1000	1.1 V ± 50 mV	0 to 105	Modified core frequency and voltage to reduce power consumption, modified processor bus AC timing.
MC7457RX1000NC				
MC7447RX867NB	867			
MC7457RX867NC				
MC7447RX733NB	733			
MC7457RX733NC				
MC7447RX600NB	600			
MC7457RX600NC				

2 Features

This section summarizes changes to the features of the MPC7457 described in the *MPC7457 RISC Microprocessor Hardware Specifications*.

- Power management
  - 1.1-V processor core

3 General Parameters

- Core power supply: 1.1 V ± 50 mV DC nominal

5.1 DC Electrical Characteristics

Table 4 provides the recommended operating conditions for the MPC7457 part numbers described herein.

Table 4. Recommended Operating Conditions[1]

Characteristic	Symbol	Recommended Value	Unit	Notes
Core supply voltage	V_{DD}	1.1 V ± 50 mV	V	
PLL supply voltage	AV_{DD}	1.1 V ± 50 mV	V	2

Notes:

1. These are the recommended and tested operating conditions. Proper device operation outside of these conditions is not guaranteed.
2. This voltage is the input to the filter discussed in *MPC7457 RISC Microprocessor Hardware Specifications*, Section 9.2, “PLL Power Supply Filtering,” and not necessarily the voltage at the AV_{DD} pin, which may be reduced from V_{DD} by the filter.

Table 7 provides the power consumption for the MPC7457 part numbers described herein.

Table 7. Power Consumption for MPC7457

	Processor (CPU) Frequency				Unit	Notes
	600 MHz	733 MHz	867 MHz	1000 MHz		
Full-Power Mode						
Typical	5.3	6.3	7.3	8.3	W	1, 3
Maximum	7.9	9.1	10.3	11.5	W	1, 2
Doze Mode						
Typical	—	—	—	—	W	4
Nap Mode						
Typical	1.3	1.3	1.3	1.3	W	1, 2
Sleep Mode						
Typical	1.2	1.2	1.2	1.2	W	1, 2
Deep Sleep Mode (PLL Disabled)						
Typical	1.1	1.1	1.1	1.1	W	1, 3

Notes:

1. These values apply for all valid processor bus and L3 bus ratios. The values do not include I/O supply power (OV_{DD} and GV_{DD}) or PLL supply power (AV_{DD}). OV_{DD} and GV_{DD} power is system dependent, but is typically <5% of V_{DD} power. Worst case power consumption for AV_{DD} < 3 mW.
2. Maximum power is the maximum measured at nominal V_{DD} and maximum operating junction temperature (see Table 4) while running an entirely cache-resident, contrived sequence of instructions which keep all the execution units maximally busy.
3. Typical power is an average value measured at the nominal recommended V_{DD} (see Table 4) and 65°C while running the Dhrystone 2.1 benchmark and achieving 2.3 Dhrystone MIPs/MHz.
4. Doze mode is not a user-definable state; it is an intermediate state between full-power and either nap or sleep mode. As a result, power consumption for this mode is not tested.

Table 8 provides the clock AC timing specifications for the MPC7457 part numbers described herein.

Table 8. Clock AC Timing Specifications

At recommended operating conditions. See Table 4.

Characteristic	Symbol	Maximum Processor Core Frequency								Unit	Notes
		600 MHz		733 MHz		867 MHz		1000 MHz			
		Min	Max	Min	Max	Min	Max	Min	Max		
Processor frequency	f_{core}	500	600	500	733	500	867	500	1000	MHz	1
VCO frequency	f_{VCO}	1000	1200	1000	1466	1000	1733	1000	2000	MHz	1
SYSCLK frequency	f_{SYSCLK}	33	167	33	167	33	167	33	167	MHz	1, 2
SYSCLK cycle time	t_{SYSCLK}	6.0	30	6.0	30	6.0	30	6.0	30	ns	2

Note:

1. **Caution**: The SYSCLK frequency and PLL_CFG[0:4] settings must be chosen such that the resulting SYSCLK (bus) frequency, CPU (core) frequency, and PLL (VCO) frequency do not exceed their respective maximum or minimum operating frequencies. Refer to the PLL_CFG[0:4] signal description in *MPC7457 RISC Microprocessor Hardware Specifications*, Section 1.9.1, “PLL Configuration,” for valid PLL_CFG[0:4] settings.
2. Assumes lightly-loaded, single-processor system; see *MPC7457 RISC Microprocessor Hardware Specifications*, Section 5.2.1, “Clock AC Specifications” for more information.

5.2.2 Processor Bus AC Specifications

Table 9 provides the processor bus AC timing specifications for the MPC7457 part numbers described herein.

Table 9. Processor Bus AC Timing Specifications [1]

At recommended operating conditions. See Table 4.

Parameter	Symbol [2]	All Speed Grades		Unit	Notes
		Min	Max		
Input setup times:				ns	
A[0:35], AP[0:4]	t_{AVKH}	2.0	—		
D[0:63], DP[0:7]	t_{DVKH}	2.0	—		
AACK, ARTRY, BG, CKSTP_IN, DBG, DTI[0:3], GBL, TT[0:3], QACK, TA, TBEN, TEA, TS, EXT_QUAL, PMON_IN, SHD[0:1], BMODE[0:1], BVSEL, L3VSEL	t_{IVKH}	2.0	—		
BMODE[0:1], BVSEL, L3VSEL	t_{MVKH}	2.0	—		8
Input hold times:				ns	
A[0:35], AP[0:4]	t_{AXKH}	0	—		
D[0:63], DP[0:7]	t_{DXKH}	0	—		
AACK, ARTRY, BG, CKSTP_IN, DBG, DTI[0:3], GBL, TT[0:3], QACK, TA, TBEN, TEA, TS, EXT_QUAL, PMON_IN, SHD[0:1]	t_{IXKH}	0	—		
BMODE[0:1], BVSEL, L3VSEL	t_{MXKH}	0	—		8
Output valid times:				ns	
A[0:35], AP[0:4]	t_{KHAV}	—	2.0		
D[0:63], DP[0:7]	t_{KHDV}	—	2.0		
AACK, ARTRY, BR, CI, CKSTP_IN, DRDY, DTI[0:3], GBL, HIT, PMON_OUT, QREQ, TBST, TSIZ[0:2], TT[0:3], TS, SHD[0:1], WT	t_{KHOV}	—	2.0		

Table 9. Processor Bus AC Timing Specifications [1] (continued)

At recommended operating conditions. See Table 4.

Parameter	Symbol [2]	All Speed Grades		Unit	Notes
		Min	Max		
Output hold times: A[0:35], AP[0:4] D[0:63], DP[0:7] AACK, ARTRY, BR, CI, CKSTP_IN, DRDY, DTI[0:3], GBL, HIT, PMON_OUT, QREQ, TBST, TSIZ[0:2], TT[0:3], TS, SHD[0:1], WT	 t_{KHAX} t_{KHDX} t_{KHOX}	 0.5 0.5 0.5	 — — —	ns	
SYSCLK to output enable	t_{KHOE}	0.5	—	ns	
SYSCLK to output high impedance (all except TS, ARTRY, SHD0, SHD1)	t_{KHOZ}	—	3.5	ns	
SYSCLK to TS high impedance after precharge	t_{KHTSPZ}	—	1	t_{SYSCLK}	3, 4, 5
Maximum delay to ARTRY/SHD0/SHD1 precharge	t_{KHARP}	—	1	t_{SYSCLK}	3, 5, 6, 7
SYSCLK to ARTRY/SHD0/SHD1 high impedance after precharge	t_{KHARPZ}	—	2	t_{SYSCLK}	3, 5, 6, 7

Notes:

1. All input specifications are measured from the midpoint of the signal in question to the midpoint of the rising edge of the input SYSCLK. All output specifications are measured from the midpoint of the rising edge of SYSCLK to the midpoint of the signal in question. All output timings assume a purely resistive 50-Ω load. Input and output timings are measured at the pin; time-of-flight delays must be added for trace lengths, vias, and connectors in the system.
2. The symbology used for timing specifications herein follows the pattern of $t_{\text{(signal)(state)(reference)(state)}}$ for inputs and $t_{\text{(reference)(state)(signal)(state)}}$ for outputs. For example, t_{IVKH} symbolizes the time input signals (I) reach the valid state (V) relative to the SYSCLK reference (K) going to the high (H) state or input setup time. And t_{KHOV} symbolizes the time from SYSCLK(K) going high (H) until outputs (O) are valid (V) or output valid time. Input hold time can be read as the time that the input signal (I) went invalid (X) with respect to the rising clock edge (KH) (note the position of the reference and its state for inputs) and output hold time can be read as the time from the rising edge (KH) until the output went invalid (OX).
3. t_{sysclk} is the period of the external clock (SYSCLK) in ns. The numbers given in the table must be multiplied by the period of SYSCLK to compute the actual time duration (in ns) of the parameter in question.
4. According to the bus protocol, TS is driven only by the currently active bus master. It is asserted low then precharged high before returning to high impedance. The nominal precharge width for TS is $0.5 \times t_{SYSCLK}$, that is, less than the minimum t_{SYSCLK} period, to ensure that another master asserting TS on the following clock will not contend with the precharge. Output valid and output hold timing is tested for the signal asserted. Output valid time is tested for precharge.The high-impedance behavior is guaranteed by design.
5. Guaranteed by design and not tested.
6. According to the bus protocol, ARTRY can be driven by multiple bus masters through the clock period immediately following AACK. Bus contention is not an issue because any master asserting ARTRY will be driving it low. Any master asserting it low in the first clock following AACK will then go to high impedance for one clock before precharging it high during the second cycle after the assertion of AACK. The nominal precharge width for ARTRY is 1.0 t_{SYSCLK}; that is, it should be high impedance before the first opportunity for another master to assert ARTRY. Output valid and output hold timing is tested for the signal asserted.The high-impedance behavior is guaranteed by design.
7. According to the MPX bus protocol, SHD0 and SHD1 can be driven by multiple bus masters beginning the cycle of TS. Timing is the same as ARTRY, that is, the signal is high impedance for a fraction of a cycle, then negated for up to an entire cycle (crossing a bus cycle boundary) before being three-stated again. The nominal precharge width for SHD0 and SHD1 is 1.0 t_{SYSCLK}. The edges of the precharge vary depending on the programmed ratio of core to bus (PLL configurations).
8. BMODE[0:1] and BVSEL are mode select inputs and are sampled before and after HRESET negation. These parameters represent the input setup and hold times for each sample. These values are guaranteed by design and not tested. These inputs must remain stable after the second sample.

5.2.3 L3 Clock AC Specifications

The MPC7457 devices described by this part number specification conform to the L3 clock AC timing specifications provided in the *MPC7457 RISC Microprocessor Hardware Specifications*. Refer to the hardware specifications for additional information.

5.2.4 L3 Bus AC Specifications

The MPC7457 devices described by this part number specification conform to the L3 clock AC timing specifications provided in the *MPC7457 RISC Microprocessor Hardware Specifications*. Refer to the hardware specifications for additional information.

11 Ordering Information

11.1 Part Numbers Addressed by This Specification

Table 22 provides the ordering information for the MPC7457 parts described in this document.

Table 22. Part Marking Nomenclature

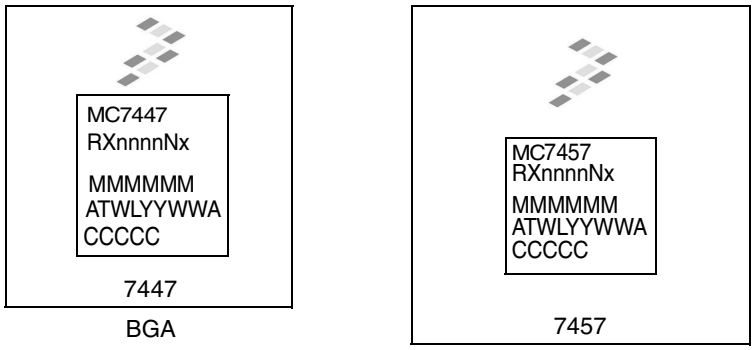
xxx	**74*n*7**	**RX**	***nnnn***	**N**	***x***
Product Code	**Part Identifier**	**Package**	**Processor Frequency** [1]	**Application Modifier**	**Revision Level**
MC	7447	RX = CBGA	1000	N: 1.1 V ± 50 mV 0° to 105°C	B: 1.1:PVR = 8002 0101
			867		
			733		
			600		
	7457		1000		C: 1.2:PVR = 8002 0102
			867		
			733		
			600		

Note:

1. Processor core frequencies supported by parts addressed by this specification only. Parts addressed by other specifications may support other maximum core frequencies.

11.3 Part Marking

Parts are marked as the example shown in Figure 29.



Notes:
MMMMMM is the 6-digit mask number.
ATWLYYWWA is the traceability code.
CCCCC is the country of assembly. This space is left blank if parts are assembled in the United States.

Figure 29. Freescale Part Marking for BGA Devices

Document Revision History

Table B provides a revision history for this hardware specification addendum.

Table B. Document Revision History

Rev. No.	Date	Substantive Change(s)
3	1/27/2005	Corrected numerous errors in lists of pins associated with t_{KHOV}, t_{KHOX}, t_{IVKH}, and t_{IXKH} in Table 9
		Removed PPC devices; added Rev 1.2 (Rev C) devices: • MC7457RX1000NC • MC7457RX867NC • MC7457RX733NC • MC7457RX600NC
		Changed name of document from *MPC7457 Part Number Specification for the MPC74x7RX*nnnn*N*x *Series* to *MPC7457 Hardware Specification Addendum for the MPC74*n*7RX*nnnn*N*x *Series*. Previous document order number was MPC7457RXNXPNS.
2	—	Added “MC7447...” part numbers to reflect qualification status.
		Table 8: Increased maximum system bus frequency (f_{SYSCLK}) to 167 MHz.
		Table 9: Corrected numerous errors in lists of pins associated with t_{KHOV}, t_{KHOX}, t_{IVKH}, and t_{IXKH}. Updated (improved) AC timing parameters based on latest characterization data.
		Added 867, 733, and 600 MHz speed grades.
		Removed Tables 10, 13, and 14: devices described by this specification conform to the AC timing found in the *MPC7457 RISC Microprocessor Hardware Specifications*.
		Corrected typo in Figure 29: 7447 device was incorrectly marked...RX10000NB.
1	—	Corrected product code in part numbers on page 1 and in Table A.
		Updated power consumption specifications in Table 7.
		Corrected product code in Section 1.11 and Table 21.
0.1	—	Edited introductory paragraphs to clarify which part numbers are affected by this specification.
0	—	Initial release.

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